

What is claimed is:

1. A plugging method for a printed circuit board having a plurality of first circuit patterns formed on a surface of the board, a plurality of second circuit patterns formed in the board, comprising the steps of:

filling a solder resist or resin in spaces between the first circuit patterns;
grinding the surface of the board; and
performing a two dimensional plating on an upper surface of the first pattern.

2. The method of claim 1, wherein the two dimensional plating is a gold plating.

3. A method for manufacturing a printed circuit board having a plurality of circuit patterns formed on a surface of the board and formed in the board and a plurality of holes for electrically connecting the circuit patterns, comprising the steps of:

filling a solder resist or resin in spaces between the circuit patterns formed on the surface of the board;

grinding the surface of the board and exposing an upper surface of the circuit patterns formed on the surface of the board; and

performing a two dimensional plating on the exposed upper surface of the circuit pattern formed on the surface of the board.

4. The method of claim 3, wherein the two dimensional plating is a gold plating.

5. The method of claim 1, wherein the solder resist or insulating resin is plugged into the hole by moving the squeegee under the condition of being abutted directly on the upper surface of the hole.

6. The method of claim 1, wherein the step of filling the solder resister or resin comprises;

a first step of plugging the solder resist or insulating resin in one portion of the hole by moving the squeegee under the condition of being abutted on the upper surface of the hole; and

a second step of completely plugging the solder resist or insulating resin in the whole portion of the hole by moving the squeegee under the condition of being abutted on the upper surface of the hole.

7. The method of claim 6, wherein in the second plugging step the solder resist or insulating resin is plugged in the hole by moving the squeegee in the opposite direction to the moving direction of the squeegee in the first plugging step.

8. The method of claim 6, wherein in the second plugging step the solder resist or insulating resin is plugged in the hole by moving the squeegee in the same direction to the moving direction of the squeegee in the first plugging step.

9. The method of claim 1, wherein the solder resist or insulating resin is coated only on an area exposed by a mask for selectively exposing the plurality of circuit patterns formed on the printed circuit board at a predetermined interval or on the hole.

10. The method of claim 1, wherein the solder resist or insulating resin filled in the spaces among the surface side circuit patterns is filled to the same height as the upper surface of the circuit patterns.

11. The method of claim 3, wherein the solder resist or insulating resin is plugged into the hole by moving the squeegee under the condition of being abutted directly on the upper surface of the hole.

12. The method of claim 3, wherein the step of filling the solder resistor or resin comprises;

a first step of plugging the solder resist or insulating resin in one portion of the hole by moving the squeegee under the condition of being abutted on the upper surface of the hole; and

a second step of completely plugging the solder resist or insulating resin in the whole portion of the hole by moving the squeegee under the condition of being abutted on the upper surface of the hole.

13. The method of claim 12, wherein in the second plugging step the solder resist or insulating resin is plugged in the hole by moving the squeegee in

the opposite direction to the moving direction of the squeegee in the first plugging step.

14. The method of claim 12, wherein in the second plugging step the solder resist or insulating resin is plugged in the hole by moving the squeegee in the same direction to the moving direction of the squeegee in the first plugging step.

15. The method of claim 3, wherein the solder resist or insulating resin is coated only on an area exposed by a mask for selectively exposing the plurality of circuit patterns formed on the printed circuit board at a predetermined interval or on the hole.

16. The method of claim 3, wherein the solder resist or insulating resin filled in the spaces among the surface side circuit patterns is filled to the same height as the upper surface of the circuit patterns.